Ablebond 789-3

Epoxy; Epoxide

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Message:

ABLEBOND® 789-3™ die attach adhesive is designed for microelectronic applications. This adhesive exhibits strong adhesion to difficult-to-bond metals and retains its bond strength after exposure to moisture.

General Information		
Features	Bondability Electrically Insulating Moisture Resistant	
Uses	Adhesives	
Appearance	Amber	
Forms	Paste	
Thermal	**Nominal Value**	**Unit**
Glass Transition Temperature	126	°C
CLTE - Flow		
< 126°C	6.3E-5	cm/cm/°C
> 126°C	1.4E-4	cm/cm/°C
Thermal Conductivity (121°C)	0.30	W/m/K
Electrical	**Nominal Value**	**Unit**
Volume Resistivity	2.0E+14	ohms·cm
Dielectric Strength	31	kV/mm
Thermoset	**Nominal Value**	**Unit**
Pot Life (25°C)	130000	min
Shelf Life		
-40°C	52	wk
5°C	26	wk
Post Cure Time		
93°C	4.0	hr
150°C	0.50	hr
Fill Analysis	**Nominal Value**	**Unit**
Brookfield Viscosity - CP51 (25°C) [1]	36.5	Pa·s
Lap Shear		
Al to Al : 25°C	34.5	MPa
Au to Au : 25°C	37.9	MPa
Shear Strength - Die (Ceramic) [2]	27.6	MPa
Weight Loss on Heating (250°C)	0.28	%
NOTE		

1.	Speed 5 rpm
2.	2 X 2 mm Si die